DECLARATION FOR PATENT APPLICATION (WITH POWER OF ATTORNEY)

As an inventor named below or on any attached continuation page, I hereby declare that: My residence, post office address and citizenship are as stated next to my name.

I believe that I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled METHODS AND APPARATUS RELATING TO SINGULATING SEMICONDUCTOR WAFERS AND WAFER SCALE ASSEMBLIES, the specification of which (check one):

	is attached hereto. was filed on was amended on was filed on was amended under PCT Arti	as United States application. as PCT international application.	on serial no	and and
	state that I have reviewed an icluding the claims, as amend			
known to me to	wledge the duty to disclose to be material to the patentabili defined in Title 37, Code of I	ty of the subject matter clair		
365(b) of any for international applisted below an attached continuinternational approximately.	claim foreign priority benefication(s) for pater oplication(s) designating at least on any attached continuation uation page any foreign application(s) designating at least date before that of the application	nt or inventor's certificate of ast one country other than the n page and have also identification for patent or inventor ast one country other than the	r § 365(a) of the United S fied below 's certificate United S	of any PCT tates of America and on any te or any PCT
Prior foreign/P	CT application(s):		Priority	Claimed
(number) (country)	(day/month/year filed)	Yes	No
(number) (country)	(day/month/year filed)	Yes	No

I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s) or § 365(c) of PCT international application(s) designating the United States of America listed below and on any attached continuation page and, insofar as the subject matter of each of the claims of this application is not disclosed in any such prior application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose to the U.S. Patent and Trademark Office all information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations § 1.56 which became available

DECLARATION FOR PATENT APPLICATION

(continuation page)

Invention Title: METHODS AND APPARATUS RELATING TO SINGULATING SEMICONDUCTOR WAFERS AND WAFER SCALE ASSEMBLIES

between the filing date of such prior application and the national or PCT international filing date of this application:

(application serial no.)	(filing date)	(status-pending, patented or abandoned)
(application serial no.)	(filing date)	(status-pending, patented or abandoned)
I hereby claim the benefit u provisional application(s) listed bel	•	tes Code, § 119(e) of any United States
(provisional application no.)	(filing date)	

I hereby appoint the following Registered Practitioners to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith:

David V. Trask, Reg. No. 22,012
Laurence B. Bond, Reg. No. 30,549
James R. Duzan, Reg. No. 28,393
Allen C. Turner, Reg. No. 33,041
Kent S. Burningham, Reg. No. 30,453
Kevin K. Johanson, Reg. No. 38,506
Bretton L. Crockett, Reg. No. 44,632
Bradley B. Jensen, Reg. No. 46,801
Greg T. Warder, Reg. No. 50,208
Marcus S. Simon, Reg. No. 50,258
G. Scott Dorland, Ph.D., Reg. No. 51,622
Michael L. Lynch, Reg. No. 30,871

William S. Britt, Reg. No. 20,969
Joseph A. Walkowski, Reg. No. 28,765
H. Dickson Burton, Reg. No. 48,396
Edgar R. Cataxinos, Reg. No. 39,931
Brick G. Power, Reg. No. 38,581
Krista Weber Powell, Reg. No. 47,867
Tawni L. Wilhelm, Reg. No. 47,456
Andrew F. Nilles, Reg. No. 47,628
Trent N. Butcher, Reg. No. 51,518
Jeffery M. Michelsen, Reg. No. 50,978
Charles B. Brantley II, Reg. No. 38,086

Address all correspondence to: Joseph A. Walkowski, telephone no. (801) 532-1922.

TRASKBRITT, PC P.O. Box 2550 Salt Lake City, Utah 84110

DECLARATION FOR PATENT APPLICATION

(continuation page)

Invention Title: METHODS AND APPARATUS RELATING TO SINGULATING SEMICONDUCTOR WAFERS AND WAFER SCALE ASSEMBLIES

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of first joint inventor: Salman Akram

Inventor's signature

Salan Akan Date March 1st 2004

Residence: Boise, Idaho Citizenship: U.S.A.

Post Office Address: 1463 E. Regatta, Boise, Idaho 83706

Document in ProLaw